**IGBT Module** 

# **STARPOWER**

SEMICONDUCTOR™

# **GD200HFU120C2S**

**Molding Type Module** 

#### 1200V/200A 2 in one-package

#### **General Description**

STARPOWER IGBT Power Module provides ultrafast switching speed as well as short circuit ruggedness. It's designed for the applications such as electronic welder and Inductive heating.

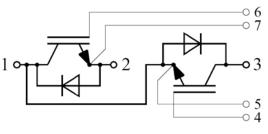
**IGBT** 

#### Features

- NPT IGBT technology
- 10µs short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(sat)}$  with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

## **Typical Applications**

- Switching mode power supplies
- Inductive heating
- Electronic welder



Equivalent Circuit Schematic

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Symbol	Description	GD200HFU120C2S	Units	
V <sub>CES</sub>	Collector-Emitter Voltage	1200	V	
V <sub>GES</sub>	Gate-Emitter Voltage	±20	V	
т	Collector Current @ $T_C=25$ °C	330	•	
I <sub>C</sub>	@ T <sub>C</sub> =80°C	200	А	
I <sub>CM(1)</sub>	Pulsed Collector Current t <sub>p</sub> =1ms	400	А	
I <sub>F</sub>	Diode Continuous Forward Current	200	А	
I <sub>FM(1)</sub>	Diode Maximum Forward Current	400	А	
P <sub>D</sub>	Maximum power Dissipation @ T <sub>j</sub> =150°C	1316	W	
T <sub>SC</sub>	Short Circuit Withstand Time @ T <sub>j</sub> =125°C		μs	
Tj	Maximum Junction Temperature		°C	
T <sub>STG</sub> Storage Temperature Range		-40 to +125	°C	
V <sub>ISO</sub>	Isolation Voltage RMS,f=50Hz,t=1min	2500	V	
Mounting Torgue	Power Terminal Screw:M6	2.5 to 5.0	N.m	
Mounting Torque	Mounting Screw:M6	3.0 to 6.0	N.m	

## Absolute Maximum Ratings $T_C=25$ °C unless otherwise noted

#### Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

## Electrical Characteristics of IGBT $T_C=25$ °C unless otherwise noted

#### **Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>(BR)CES</sub>	Collector-Emitter	T <sub>i</sub> =25℃	1200			v
	Breakdown Voltage	J				
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V,$			5.0	mA
		T <sub>j</sub> =25℃				
I <sub>GES</sub>	Gate-Emitter Leakage	$V_{GE} = V_{GES}, V_{CE} = 0V,$			400	nA
	Current	T <sub>j</sub> =25℃			400	

#### **On Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>GE(th)</sub>	Gate-Emitter Threshold	$I_C=2.0mA, V_{CE}=V_{GE},$	4.4	4.9	6.0	V
	Voltage	T <sub>j</sub> =25℃	4.4			
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	$I_{\rm C}$ =200A, $V_{\rm GE}$ =15V,		3.10	3.60	v
		T <sub>j</sub> =25℃				
		$I_{\rm C}$ =200A, $V_{\rm GE}$ =15V,		3.45		
		$I_{C}=200A, V_{GE}=15V,$ $T_{j}=125$ °C				

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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t <sub>d(on)</sub>	Turn-On Delay Time	_		577		ns
t <sub>r</sub>	Rise Time			120		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			540		ns
t <sub>f</sub>	Fall Time	$V_{CC}=600V,I_{C}=200A,$		123		ns
Eon	Turn-On Switching Loss	$- R_{G} = 4.7\Omega, V_{GE} = \pm 15V, L = 200nH, T_{j} = 25^{\circ}C$		16.3		mJ
E <sub>off</sub>	Turn-Off Switching Loss			12.0		mJ
t <sub>d(on)</sub>	Turn-On Delay Time			609		ns
t <sub>r</sub>	Rise Time			121		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			574		ns
t <sub>f</sub>	Fall Time	$ V_{CC} = 600 V, I_C = 200 A,  R_G = 4.7 \Omega, V_{GE} = \pm 15 V,  L = 200 nH, T_j = 125 °C $		132		ns
Eon	Turn-On Switching Loss			22.0		mJ
E <sub>off</sub>	Turn-Off Switching Loss			16.2		mJ
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =30V,f=1MHz, V <sub>GE</sub> =0V		16.9		nF
C <sub>oes</sub>	Output Capacitance			1.51		nF
C <sub>res</sub>	Reverse Transfer Capacitance			0.61		nF
I <sub>SC</sub>	SC Data	$\begin{array}{c} T_{P} \leqslant 10 \mu s, V_{GE} = 15 V, \\ T_{j} = 25 ^{\circ} C, V_{CC} = 600 V, \\ V_{CEM} \leqslant 1200 V \end{array}$		1800		A
R <sub>Gint</sub>	Internal Gate Resistance			2.0		Ω
L <sub>CE</sub>	Stray Inductance				18	nH
R <sub>CC'+EE'</sub>	Module Lead Resistance, Terminal To Chip	T <sub>C</sub> =25℃		0.32		mΩ

## Switching Characteristics

# **Electrical Characteristics of DIODE** $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V <sub>F</sub>	Diode Forward	I -200 A	Tj=25℃		1.82	2.25	V
	Voltage	I <sub>F</sub> =200A	T <sub>j</sub> =125℃		1.95		V
Qr	Recovered Charge		Tj=25℃		13.1		
		I <sub>F</sub> =200A,	T <sub>j</sub> =125℃		26.1		μC
I <sub>RM</sub>	Peak Reverse	V <sub>R</sub> =600V,	Tj=25℃		123		А
	Recovery Current	di/dt=-1800A/µs,	T <sub>j</sub> =125℃		172		
E <sub>rec</sub>	Reverse Recovery	V <sub>GE</sub> =-15V	T <sub>j</sub> =25℃		7.0		mI
	Energy		Tj=125℃		12.9		mJ

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# **Thermal Characteristics**

Symbol	Parameter		Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.095	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.140	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
G	Weight of Module	300		g

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#### GD200HFU120C2S

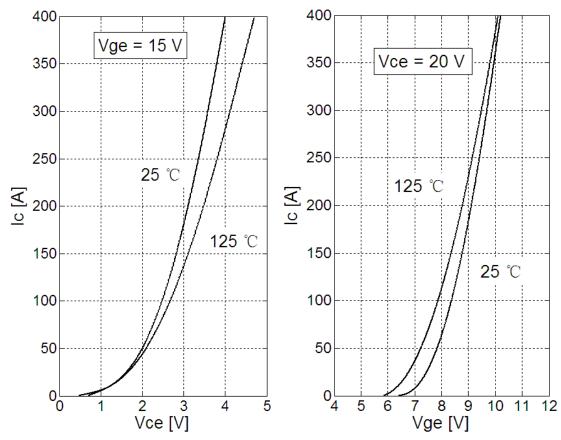
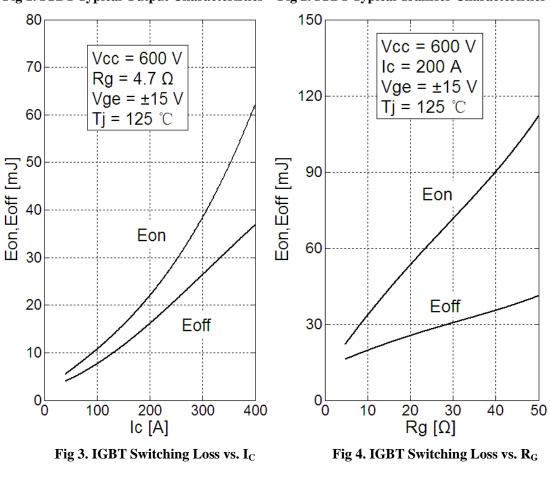


Fig 1. IGBT Typical Output Characteristics Fig 2. IGBT Typical Transfer Characteristics

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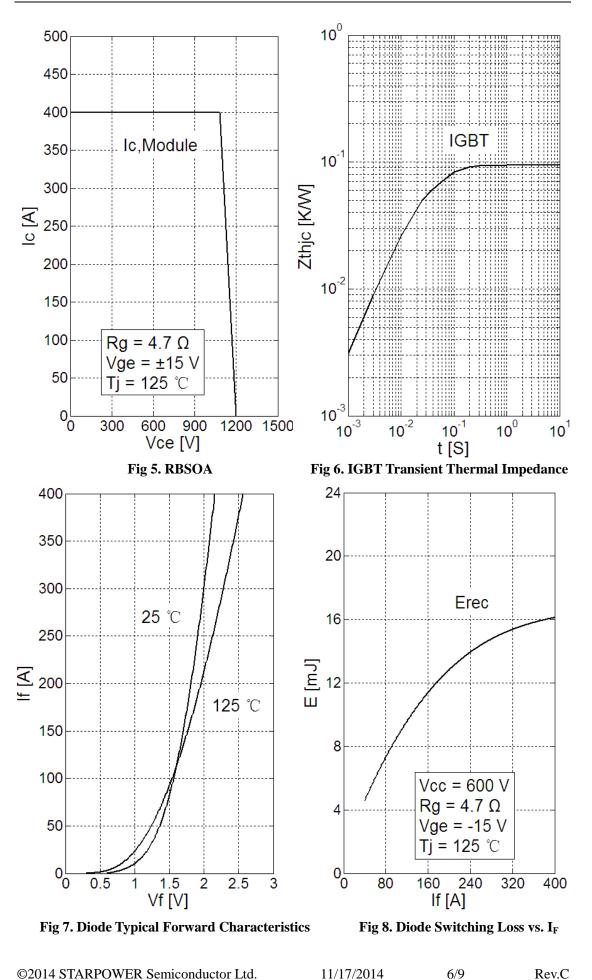
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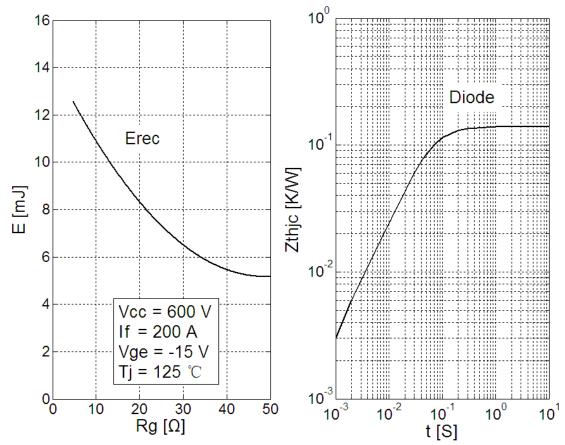


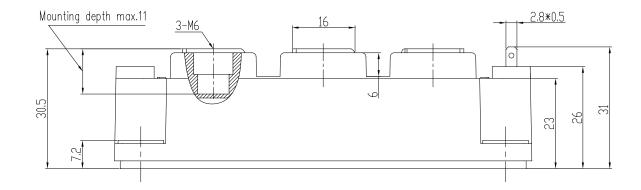
Fig 9. Diode Switching Loss vs. R<sub>G</sub>

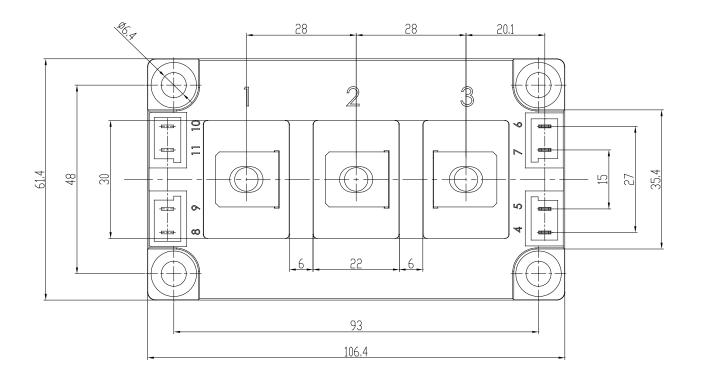
Fig 10. Diode Transient Thermal Impedance

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# **Package Dimension**

**Dimensions in Millimeters** 





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